

Electronic Patent Application Fee Transmittal

Application Number:	10527604			
Filing Date:	15-Mar-2005			
Title of Invention:	THERMOPLASTIC RESIN COMPOSITION AND MOLDINGS THEREOF			
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Filer:	Thomas Daniel Christenbury/Carol Coney			
Attorney Docket Number:	SPL-05-1048			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1810